

Type number	Package	Package description	Total product weight
74LVC4245ABQ	SOT815-1	DHVQFN24	50.44490 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935285619118	10	1	260	30 s	1	240	20 s	3	Bangkok, Thailand; Suzhou, China; Shanghai, China	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.16821	80.10000	0.33345
		Polymer	Resin system	Proprietary	0.04179	19.90000
			subTotal		0.21000	100.00000
Die	Doped silicon	Silicon (Si)	7440-21-3	0.61828	100.00000	1.22565
			subTotal	0.61828	100.00000	1.22565
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	18.35360	97.47000	36.38346
		Iron (Fe)	7439-89-6	0.45192	2.40000	0.89587
		Phosphorous (P)	7723-14-0	0.00565	0.03000	0.01120
		Zinc (Zn)	7440-66-6	0.01883	0.10000	0.03733
			subTotal		18.83000	100.00000
Mould Compound	Filler	Silica -amorphous-	7631-86-9	2.10000	7.00000	4.16296
		Silica fused	60676-86-0	24.90000	83.00000	49.36079
	Pigment	Carbon black	1333-86-4	0.15000	0.50000	0.29735
		Polymer	Epoxy resin system	Proprietary	1.80000	6.00000
		Phenolic resin	Proprietary	1.05000	3.50000	2.08148
		subTotal		30.00000	100.00000	59.47083
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.01920	3.00000	0.03806
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.59072	92.30000	1.17102
		Palladium (Pd)	7440-05-3	0.01984	3.10000	0.03933
		Silver (Ag)	7440-22-4	0.01024	1.60000	0.02030
			subTotal		0.64000	100.00000
Wire	Pure metal	Copper (Cu)	7440-50-8	0.14662	100.00000	0.29065
			subTotal	0.14662	100.00000	0.29065

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.